

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6343720

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the TYPOGRAPHICAL ERROR MADE TO THE 7TH INVENTOR'S NAME ON THE COVER SHEET FROM "CHIAHUNA LIU" TO "CHIAHUNG LIU" previously recorded on Reel 053826 Frame 0428. Assignor(s) hereby confirms the IS TO CORRECT A TYPOGRAPHICAL ERROR IN THE COVER SHEET PREVIOUSLY RECORDED ON 09/21/2020.

CONVEYING PARTY DATA

Name	Execution Date
YING-CHENG TSENG	11/01/2018
YU-CHIH HUANG	11/01/2018
CHIH-HSUAN TAI	11/01/2018
TING-TING KUO	11/01/2018
CHI-HUI LAI	11/01/2018
BAN-LI WU	11/02/2018
CHIAHUNG LIU	11/01/2018
HAO-YI TSAI	11/05/2018

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6 HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16215325

CORRESPONDENCE DATA

Fax Number: (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Email: docketing@slatermatsil.com

Correspondent Name: SLATER MATSIL, LLP/TSMC

Address Line 1: 17950 PRESTON ROAD, SUITE 1000

Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSMP20180499US00
NAME OF SUBMITTER:	CINDY STOUTEN
SIGNATURE:	/Cindy Stouten/
DATE SIGNED:	10/09/2020
Total Attachments: 3 source=TSMP20180499US00-Assignment-with-cover-sheet#page1.tif source=TSMP20180499US00-Assignment-with-cover-sheet#page2.tif source=TSMP20180499US00-Assignment-with-cover-sheet#page3.tif	

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6307925

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YING-CHENG TSENG	11/01/2018
YU-CHIH HUANG	11/01/2018
CHIH-HSUAN TAI	11/01/2018
TING-TING KUO	11/01/2018
CHI-HUI LAI	11/01/2018
BAN-LI WU	11/02/2018
CHIAHUNA LIU	11/01/2018
HAO-YI TSAI	11/05/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	8, LI-HSIN RD. 6 HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16215325
CORRESPONDENCE DATA	
Fax Number:	(972)732-9218
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	9727321001
Email:	docketing@slatermatsil.com
Correspondent Name:	SLATER MATSIL, LLP
Address Line 1:	17950 PRESTON ROAD, SUITE 1000
Address Line 4:	DALLAS, TEXAS 75252
ATTORNEY DOCKET NUMBER:	TSMP20180499US00
NAME OF SUBMITTER:	CINDY STOUTEN
SIGNATURE:	/Cindy Stouten/

Jc (2)

ATTORNEY DOCKET NO.
TSMPT20180499US00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	SEMICONDUCTOR DEVICE WITH MULTIPLE POLARITY GROUPS			
SIGNATURE OF INVENTOR AND NAME	<i>Ying-Cheng Tseng</i> Ying-Cheng Tseng	<i>Yu-Chih Huang</i> Yu-Chih Huang	<i>Chih-Hsuan Tai</i> Chih-Hsuan Tai	<i>Ting-Ting Kuo</i> Ting-Ting Kuo
DATE	2018/11/1	2018/11/1	2018/11/1	2018/11/1
RESIDENCE	Tainan, Taiwan	Hsinchu, Taiwan	Taipei, Taiwan	Hsinchu, Taiwan

ATTORNEY DOCKET NO.
TSM20180499US00

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year,

TITLE OF INVENTION	SEMICONDUCTOR DEVICE WITH MULTIPLE POLARITY GROUPS			
SIGNATURE OF INVENTOR AND NAME	<i>Chi-Hui Lai</i> Chi-Hui Lai	<i>Ban-Li Wu</i> Ban-Li Wu	<i>Chiahung Liu</i> Chiahung Liu	<i>Hao-Yi Tsai</i> Hao-Yi Tsai
DATE	2018.11.12	2018.11.2	2018.11.1	2018.11.5
RESIDENCE	Taichung, Taiwan	Hsinchu, Taiwan	Hsinchu City, Taiwan	Hsinchu, Taiwan